Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-17 (Canceled).

18. (Original) A fabrication method, comprising the steps of:
    varying the history of wafers within a lot by transporting individual ones thereof
        within a processing tool with multiple processing chambers,
        among said chambers and wafer cassette and/or staging locations
        in various different sequences.

19. (Original) The method of Claim 18, further comprising the contemporaneous step of recording process sequence data for said wafers.

20. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step.

21. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step, and controlling process parameters accordingly.

22. (Original) A processing tool which is programmed to perform the method of Claim 1.

23. (Original) A processing tool which is programmed to perform the method of Claim 6.

24. (Original) A processing tool which is programmed to perform the method of Claim 10.

Claims 25 and 26 (Canceled).